

Flip Chip Technologies Market (By Bumping Technology: Copper Pillar, Solder Bumping, Gold Bumping; By Packaging Technology: 3D IC, 2.5D IC and 2D IC; By Packaging Type: Flip Chip SiP Package, Flip Chip PGA Package, Flip Chip BGA Package, Flip Chip LGA Package, and Wafer Level Packaging–CSPnl; By industry: Electronics, Industrial, Automotive & Transport, Healthcare, IT & Telecommunication, Aerospace and Defense; By Geography: North America, Europe, Asia-Pacific and RoW) Global Scenario, Market Size, Outlook, Trend and Forecast, 2015 – 2024

<https://marketpublishers.com/r/F0A3AC55C12EN.html>

Date: January 2018

Pages: 130

Price: US\$ 3,195.00 (Single User License)

ID: F0A3AC55C12EN

Abstracts

As per the latest report published by Variant Market Research, Global flip chip technologies market is estimated to reach \$54 billion by 2024; growing at a CAGR of 9.3% from 2016 to 2024. Flip chip, a semiconductor interconnecting device is commonly used in many electronic products like PCs, smartphones, and medical devices, among others. Flip chip technology offers various benefits such as total package size reduction, reduction in the silicon cost, decrease in signal inductance, and high signal density. Flip chip technology is widely used in various industry verticals such as IT & telecommunication, automotive & transport, electronics, industrial, healthcare, and aerospace and defence, among others.

Major factors driving the global flip chip technologies market are advantages of flip chip

technology than the traditional wire bond electrical connection, evolving internet of things, and rising demand for miniaturization & high-performing electronic devices. However, huge initial investment essential to set up new manufacturing plant may hamper the market growth. Furthermore, high acceptance of sensors in electronic devices would unfold with numerous growth opportunities in the forecasted year.

Major segments of the global flip chip technologies market are bumping technology, packaging type, packaging technology, industry vertical, and geography. Bumping technology comprises copper pillar, gold bumping, solder bumping (tin-lead eutectic solder, and lead-free solder), and other bumping technologies (aluminium & conductive polymer). By, packaging type, the market is categorized as flip chip PGA package, flip chip SiP package, flip chip BGA package, flip chip LGA package, and wafer level packaging–CSPnl. Furthermore, the market is sub segmented by packaging technology as 3D IC, 2.5D IC and 2D IC. Industry vertical is further divided into automotive & transport, electronics, industrial, healthcare, IT & telecommunication, aerospace and defence, and other industry verticals (renewable energy and media & entertainment).

Geographically, the global flip chip technologies market is categorized into North America, Europe, Asia-Pacific and RoW. The U.S., Mexico and Canada are covered under North America wherein Europe covers Germany, France, Italy, and Rest of Europe. Asia-Pacific covers China, Japan, South Korea, Taiwan, India, and Rest of Asia Pacific. Rest of the World (RoW) covers South America, Middle East and Africa.

The major players competing in the market are ASE group, Powertech Technology Inc., United Microelectronics Corporation, Intel Corporation, Siliconware Precision Industries Co., Ltd., Amkor Technology, Inc., TSMC, Jiangsu Changjiang Electronics Technology Co., Ltd., Samsung Electronics Co., and Texas Instruments, Inc., among others.

The key takeaways from the report

The report will provide detailed analysis of Flip Chip Technologies Market with respect to major segments such as bumping technology, packaging type, packaging technology, and industry vertical

The report will include the qualitative and quantitative analysis with market estimation over 2015-2022 and compound annual growth rate (CAGR) between 2016 and 2022.

Comprehensive analysis of market dynamics including factors and opportunities.

An exhaustive regional analysis of Flip Chip Technologies Market.

Profile of key players of the Flip Chip Technologies Market, which include key financials, product & services and new developments.

Scope of Flip Chip Technologies Market

Bumping Technology Segments

Copper Pillar

Gold Bumping

Solder Bumping

 Tin-lead eutectic solder

 Lead-free solder

Other Bumping Technologies (Aluminium & Conductive polymer)

Packaging Type Segments

Flip Chip PGA Package

Flip Chip SiP Package

Flip Chip BGA Package

Flip Chip LGA Package

Wafer Level Packaging–CSPnl

Packaging Technology Segments

3D IC

2.5D IC

2D IC

Industry Vertical Segments

Automotive & Transport

Electronics

Industrial

Healthcare

IT & telecommunication

Aerospace and Defence

Other Industry Verticals (Renewable Energy and Media & Entertainment)

Geographical Segments

North America

US

Canada

Mexico

Europe

Germany

France

Italy

Rest of Europe

Asia-Pacific

China

Japan

South Korea

Taiwan

India

Rest of Asia-Pacific

RoW

South America

Middle East

Africa

Contents

CHAPTER 1 PREFIX

- 1.1 Market Scope
- 1.2 Report Description
- 1.3 Research Methodology
 - 1.3.1 Primary Research
 - 1.3.2 Secondary Research
 - 1.3.3 In-house Data Modeling

CHAPTER 2 EXECUTIVE SUMMARY

- 2.1 Global Flip Chip Technologies Market Year-on-Year Growth, 2016 – 2024 (%)

CHAPTER 3 MARKET OUTLINE

- 3.1 Market Inclination, Trend, Outlook and Viewpoint
- 3.2 Market Share Analysis: Company's Competitive Scenario
- 3.3 Market Dynamics
 - 3.3.1 Drivers
 - 3.3.1.1 Impact Analysis
 - 3.3.2 Restraints
 - 3.3.2.1 Impact Analysis
 - 3.3.3 Opportunities

CHAPTER 4 GLOBAL FLIP CHIP TECHNOLOGIES MARKET BY BUMPING TECHNOLOGY: MARKET SIZE AND FORECAST, 2015 – 2024

- 4.1 Overview
- 4.2 Copper Pillar
 - 4.2.1 Current Trend and Analysis
 - 4.2.2 Market Size and Forecast, 2015 – 2024 (\$ Billion)
 - 4.2.3 Market Size and Forecast by Region, 2015 – 2024 (\$ Billion)
- 4.3 Solder Bumping
 - 4.3.1 Current Trend and Analysis
 - 4.3.2 Market Size and Forecast, 2015 – 2024 (\$ Billion)
 - 4.3.3 Market Size and Forecast by Region, 2015 – 2024 (\$ Billion)
 - 4.3.4 Tin-Lead Eutectic Solder

- 4.3.4.1 Market Size and Forecast by Region, 2015 – 2024 (\$ Billion)
- 4.3.5 Lead-Free Solder
 - 4.3.5.1 Market Size and Forecast by Region, 2015 – 2024 (\$ Billion)
- 4.4 Gold Bumping
 - 4.4.1 Current Trend and Analysis
 - 4.4.2 Market Size and Forecast, 2015 – 2024 (\$ Billion)
 - 4.4.3 Market Size and Forecast by Region, 2015 – 2024 (\$ Billion)
- 4.5 Other Bumping Technologies
 - 4.5.1 Current Trend and Analysis
 - 4.5.2 Market Size and Forecast, 2015 – 2024 (\$ Billion)
 - 4.5.3 Market Size and Forecast by Region, 2015 – 2024 (\$ Billion)

CHAPTER 5 GLOBAL FLIP CHIP TECHNOLOGIES MARKET BY PACKAGING TECHNOLOGY: MARKET SIZE AND FORECAST, 2015 – 2024

- 5.1 Overview
- 5.2 3D IC
 - 5.2.1 Current Trend and Analysis
 - 5.2.2 Market Size and Forecast, 2015 – 2024 (\$ Billion)
 - 5.2.2 Market Size and Forecast by Region, 2015 – 2024 (\$ Billion)
- 5.3 2.5D IC
 - 5.3.1 Current Trend and Analysis
 - 5.3.2 Market Size and Forecast, 2015 – 2024 (\$ Billion)
 - 5.3.2 Market Size and Forecast by Region, 2015 – 2024 (\$ Billion)
- 5.4 2D IC
 - 5.4.1 Current Trend and Analysis
 - 5.4.2 Market Size and Forecast, 2015 – 2024 (\$ Billion)
 - 5.4.2 Market Size and Forecast by Region, 2015 – 2024 (\$ Billion)

CHAPTER 6 GLOBAL ENERGY MANAGEMENT SYSTEM MARKET BY END USER: MARKET SIZE AND FORECAST, 2015 – 2024

- 6.1 Overview
- 6.2 Flip Chip SiP Package
 - 6.2.1 Current Trend and Analysis
 - 6.2.2 Market Size and Forecast, 2015 – 2024 (\$ Billion)
 - 6.2.3 Market Size and Forecast by Region, 2015 – 2024 (\$ Billion)
- 6.3 Flip Chip PGA Package
 - 6.3.1 Current Trend and Analysis

- 6.3.2 Market Size and Forecast, 2015 – 2024 (\$ Billion)
- 6.3.3 Market Size and Forecast by Region, 2015 – 2024 (\$ Billion)
- 6.4 Flip Chip BGA Package
 - 6.4.1 Current Trend and Analysis
 - 6.4.2 Market Size and Forecast, 2015 – 2024 (\$ Billion)
 - 6.4.3 Market Size and Forecast by Region, 2015 – 2024 (\$ Billion)
- 6.5 Flip Chip LGA Package
 - 6.5.1 Current Trend and Analysis
 - 6.5.2 Market Size and Forecast, 2015 – 2024 (\$ Billion)
 - 6.5.3 Market Size and Forecast by Region, 2015 – 2024 (\$ Billion)
- 6.6 Wafer Level Packaging–CSPnl
 - 6.6.1 Current Trend and Analysis
 - 6.6.2 Market Size and Forecast, 2015 – 2024 (\$ Billion)
 - 6.6.3 Market Size and Forecast by Region, 2015 – 2024 (\$ Billion)

CHAPTER 7 GLOBAL FLIP CHIP TECHNOLOGIES MARKET BY INDUSTRY VERTICAL: MARKET SIZE AND FORECAST, 2015 – 2024

- 7.1 Overview
- 7.2 Electronics
 - 7.2.1 Current Trend and Analysis
 - 7.2.2 Market Size and Forecast, 2015 – 2024 (\$ Billion)
 - 7.2.3 Market Size and Forecast by Region, 2015 – 2024 (\$ Billion)
- 7.3 Industrial
 - 7.3.1 Current Trend and Analysis
 - 7.3.2 Market Size and Forecast, 2015 – 2024 (\$ Billion)
 - 7.3.3 Market Size and Forecast by Region, 2015 – 2024 (\$ Billion)
- 7.4 Automotive & Transport
 - 7.4.1 Current Trend and Analysis
 - 7.4.2 Market Size and Forecast, 2015 – 2024 (\$ Billion)
 - 7.4.3 Market Size and Forecast by Region, 2015 – 2024 (\$ Billion)
- 7.5 Healthcare
 - 7.5.1 Current Trend and Analysis
 - 7.5.2 Market Size and Forecast, 2015 – 2024 (\$ Billion)
 - 7.5.3 Market Size and Forecast by Region, 2015 – 2024 (\$ Billion)
- 7.6 IT & Telecommunication
 - 7.6.1 Current Trend and Analysis
 - 7.6.2 Market Size and Forecast, 2015 – 2024 (\$ Billion)
 - 7.6.3 Market Size and Forecast by Region, 2015 – 2024 (\$ Billion)

7.7 Aerospace and Defence

7.7.1 Current Trend and Analysis

7.7.2 Market Size and Forecast, 2015 – 2024 (\$ Billion)

7.7.3 Market Size and Forecast by Region, 2015 – 2024 (\$ Billion)

7.8 Other Industry Verticals

7.8.1 Current Trend and Analysis

7.8.2 Market Size and Forecast, 2015 – 2024 (\$ Billion)

7.8.3 Market Size and Forecast by Region, 2015 – 2024 (\$ Billion)

CHAPTER 8 GLOBAL FLIP CHIP TECHNOLOGIES MARKET BY GEOGRAPHY: MARKET SIZE AND FORECAST, 2015 – 2024

8.1 Overview

8.1.1 Global Flip Chip Technologies Market Year-on-Year Growth, by regions 2016 – 2024 (%)

8.2 North America

8.2.1 Current Trend and Analysis

8.2.2 Market Size and Forecast, 2015 – 2024 (\$ Billion)

8.2.3 US

8.2.3.1 Market Size and Forecast, 2015 – 2024 (\$ Billion)

8.2.4 Canada

8.2.4.1 Market Size and Forecast, 2015 – 2024 (\$ Billion)

8.2.5 Mexico

8.2.5.1 Market Size and Forecast, 2015 – 2024 (\$ Billion)

8.3 Europe

8.3.1 Current Trend and Analysis

8.3.2 Market Size and Forecast, 2015 – 2024 (\$ Billion)

8.3.3 UK

8.3.3.1 Market Size and Forecast, 2015 – 2024 (\$ Billion)

8.3.4 Germany

8.3.4.1 Market Size and Forecast, 2015 – 2024 (\$ Billion)

8.3.5 France

8.3.5.1 Market Size and Forecast, 2015 – 2024 (\$ Billion)

8.3.6 Italy

8.3.6.1 Market Size and Forecast, 2015 – 2024 (\$ Billion)

8.3.7 Rest of Europe

8.3.7.1 Market Size and Forecast, 2015 – 2024 (\$ Billion)

8.4 Asia-Pacific

8.4.1 Current Trend and Analysis

8.4.2 Market Size and Forecast, 2015 – 2024 (\$ Billion)

8.4.3 China

8.4.3.1 Market Size and Forecast, 2015 – 2024 (\$ Billion)

8.4.4 Japan

8.4.4.1 Market Size and Forecast, 2015 – 2024 (\$ Billion)

8.4.5 South Korea

8.4.5.1 Market Size and Forecast, 2015 – 2024 (\$ Billion)

8.4.6 Taiwan

7.4.6.1 Market Size and Forecast, 2015 – 2024 (\$ Billion)

8.4.7 India

7.4.7.1 Market Size and Forecast, 2015 – 2024 (\$ Billion)

8.4.8 Rest of Asia-Pacific

7.4.8.1 Market Size and Forecast, 2015 – 2024 (\$ Billion)

8.5 RoW

8.5.1 Current Trend and Analysis

8.5.2 Market Size and Forecast

8.5.3 Middle East

8.5.3.1 Market Size and Forecast, 2015 – 2024 (\$ Billion)

8.5.4 South America

8.5.4.1 Market Size and Forecast, 2015 – 2024 (\$ Billion)

8.5.5 Africa

8.5.5.1 Market Size and Forecast, 2015 – 2024 (\$ Billion)

CHAPTER 9 COMPANY PROFILES

9.1 Samsung Electronics Co.

9.2 ASE group

9.3 Powertech Technology Inc.

9.4 United Microelectronics Corporation

9.5 Intel Corporation

9.6 Amkor Technology, Inc.

9.7 TSMC

9.8 Jiangsu Changjiang Electronics Technology Co., Ltd.

9.9 Texas Instruments, Inc.

9.10 Siliconware Precision Industries Co., Ltd.

List Of Figures

LIST OF FIGURES

FIG. 1 MARKET SEGMENTATION: GLOBAL FLIP CHIP TECHNOLOGIES MARKET

FIG. 2 GLOBAL FLIP CHIP TECHNOLOGIES MARKET YEAR ON YEAR GROWTH, 2016 - 2024 (%)

FIG. 3 MARKET SHARE ANALYSIS, 2016 (%)

FIG. 4 GLOBAL FLIP CHIP TECHNOLOGIES MARKET SHARE AND FORECAST, BY BUMPING TECHNOLOGY 2016 Vs 2024 (VALUE %)

FIG. 5 COPPER PILLAR MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 6 SOLDER BUMPING MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 7 GOLD BUMPING MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 8 OTHER BUMPING TECHNOLOGIES MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 9 GLOBAL FLIP CHIP TECHNOLOGIES MARKET SHARE AND FORECAST, BY PACKAGING TECHNOLOGY 2016 Vs 2024 (VALUE %)

FIG. 10 3D IC MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 11 2.5D IC MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 12 2D IC MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 13 GLOBAL FLIP CHIP TECHNOLOGIES MARKET SHARE AND FORECAST, BY PACKAGING TYPE 2016 Vs 2024 (VALUE %)

FIG. 14 FLIP CHIP SIP PACKAGE MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 15 FLIP CHIP PGA PACKAGE MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 16 FLIP CHIP BGA PACKAGE MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 17 FLIP CHIP LGA PACKAGE MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 18 WAFER LEVEL PACKAGING–CSPNL MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 19 GLOBAL FLIP CHIP TECHNOLOGIES MARKET SHARE AND FORECAST, BY INDUSTRY VERTICAL 2016 Vs 2024 (VALUE %)

FIG. 20 ELECTRONICS MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 21 INDUSTRIAL MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 22 AUTOMOTIVE & TRANSPORT MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 23 HEALTHCARE MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 24 IT & TELECOMMUNICATION MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 25 AEROSPACE AND DEFENCE MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 26 OTHER INDUSTRY VERTICALS MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 27 GLOBAL FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST BY GEOGRAPHY, 2016 Vs 2024 (REVENUE, CAGR %)

FIG. 28 GLOBAL FLIP CHIP TECHNOLOGIES MARKET YEAR ON YEAR GROWTH, BY REGIONS 2016 – 2024 (%)

FIG. 29 NORTH AMERICA FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 30 NORTH AMERICA FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST BY COUNTRY, 2015 – 2024 (\$ BILLION)

FIG. 31 U.S. FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 32 CANADA FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 33 MEXICO FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 34 EUROPE FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, 2015 – 2024, (\$ BILLION)

FIG. 35 EUROPE FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, 2015 – 2024 BY COUNTRY, (\$ BILLION)

FIG. 36 GERMANY FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 37 FRANCE FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 38 ITALY FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 39 REST OF EUROPE FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 40 ASIA-PACIFIC FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, 2015 – 2024, (\$ BILLION)

FIG. 41 ASIA-PACIFIC FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, 2015 – 2024 BY COUNTRY (\$ BILLION)

FIG. 42 CHINA FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 43 JAPAN FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, 2015 –

2024 (\$ BILLION)

FIG. 44 SOUTH KOREA FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 45 TAIWAN FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 46 INDIA FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 47 REST OF ASIA-PACIFIC FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 48 REST OF THE WORLD FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 49 REST OF THE WORLD FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, 2015 – 2024 BY COUNTRY (\$ BILLION)

FIG. 50 SOUTH AMERICA FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 51 MIDDLE EAST FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

FIG. 52 AFRICA FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, 2015 – 2024 (\$ BILLION)

List Of Tables

LIST OF TABLES

TABLE 1 GLOBAL FLIP CHIP TECHNOLOGIES MARKET SNAPSHOT

TABLE 2 GLOBAL FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, BY REGION, 2015 – 2024 (\$ BILLION)

TABLE 3 DRIVER OF THE GLOBAL FLIP CHIP TECHNOLOGIES MARKET: IMPACT ANALYSIS

TABLE 4 RESTRAINTS OF THE GLOBAL FLIP CHIP TECHNOLOGIES MARKET: IMPACT ANALYSIS

TABLE 5 COPPER PILLAR MARKET SIZE AND FORECAST, BY REGIONS, 2015 – 2024 (\$ BILLION)

TABLE 6 SOLDER BUMPING MARKET SIZE AND FORECAST, BY REGIONS, 2015 – 2024 (\$ BILLION)

TABLE 7 GOLD BUMPING MARKET SIZE AND FORECAST, BY REGIONS, 2015 – 2024 (\$ BILLION)

TABLE 8 OTHER BUMPING TECHNOLOGIES MARKET SIZE AND FORECAST, BY REGIONS, 2015 – 2024 (\$ BILLION)

TABLE 9 3D IC MARKET SIZE AND FORECAST, BY REGIONS, 2015 – 2024 (\$ BILLION)

TABLE 10 2.5D IC MARKET SIZE AND FORECAST, BY REGIONS, 2015 – 2024 (\$ BILLION)

TABLE 11 2D IC MARKET SIZE AND FORECAST, BY REGIONS, 2015 – 2024 (\$ BILLION)

TABLE 12 FLIP CHIP SIP PACKAGE MARKET SIZE AND FORECAST, BY REGIONS, 2015 – 2024 (\$ BILLION)

TABLE 13 FLIP CHIP PGA PACKAGE MARKET SIZE AND FORECAST, BY REGIONS, 2015 – 2024 (\$ BILLION)

TABLE 14 FLIP CHIP BGA PACKAGE MARKET SIZE AND FORECAST, BY REGIONS, 2015 – 2024 (\$ BILLION)

TABLE 15 FLIP CHIP LGA PACKAGE MARKET SIZE AND FORECAST, BY REGIONS, 2015 – 2024 (\$ BILLION)

TABLE 16 WAFER LEVEL PACKAGING–CSPNL MARKET SIZE AND FORECAST, BY REGIONS, 2015 – 2024 (\$ BILLION)

TABLE 17 ELECTRONICS MARKET SIZE AND FORECAST, BY REGIONS, 2015 – 2024 (\$ BILLION)

TABLE 18 INDUSTRIAL MARKET SIZE AND FORECAST, BY REGIONS, 2015 – 2024 (\$ BILLION)

TABLE 19 AUTOMOTIVE & TRANSPORT MARKET SIZE AND FORECAST, BY REGIONS, 2015 – 2024 (\$ BILLION)

TABLE 20 HEALTHCARE MARKET SIZE AND FORECAST, BY REGIONS, 2015 – 2024 (\$ BILLION)

TABLE 21 IT & TELECOMMUNICATION MARKET SIZE AND FORECAST, BY REGIONS, 2015 – 2024 (\$ BILLION)

TABLE 22 AEROSPACE AND DEFENCE MARKET SIZE AND FORECAST, BY REGIONS, 2015 – 2024 (\$ BILLION)

TABLE 23 OTHER INDUSTRY VERTICALS MARKET SIZE AND FORECAST, BY REGIONS, 2015 – 2024 (\$ BILLION)

TABLE 24 NORTH AMERICA FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, BY BUMPING TECHNOLOGY, 2015 – 2024 (\$ BILLION)

TABLE 25 NORTH AMERICA FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, BY PACKAGING TECHNOLOGY, 2015 – 2024 (\$ BILLION)

TABLE 26 NORTH AMERICA FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, BY PACKAGING TYPE, 2015 – 2024 (\$ BILLION)

TABLE 27 NORTH AMERICA FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, BY INDUSTRY VERTICAL, 2015 – 2024 (\$ BILLION)

TABLE 28 EUROPE FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, BY BUMPING TECHNOLOGY, 2015 – 2024 (\$ BILLION)

TABLE 29 EUROPE FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, BY PACKAGING TECHNOLOGY, 2015 – 2024 (\$ BILLION)

TABLE 30 EUROPE FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, BY PACKAGING TYPE, 2015 – 2024 (\$ BILLION)

TABLE 31 EUROPE FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, BY INDUSTRY VERTICAL, 2015 – 2024 (\$ BILLION)

TABLE 32 ASIA-PACIFIC FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, BY BUMPING TECHNOLOGY, 2015 – 2024 (\$ BILLION)

TABLE 33 ASIA-PACIFIC FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, BY PACKAGING TECHNOLOGY, 2015 – 2024 (\$ BILLION)

TABLE 34 ASIA-PACIFIC FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, BY PACKAGING TYPE, 2015 – 2024 (\$ BILLION)

TABLE 35 ASIA-PACIFIC FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, BY INDUSTRY VERTICAL, 2015 – 2024 (\$ BILLION)

TABLE 36 REST OF THE WORLD FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, BY BUMPING TECHNOLOGY, 2015 – 2024 (\$ BILLION)

TABLE 37 REST OF THE WORLD FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, BY PACKAGING TECHNOLOGY, 2015 – 2024 (\$ BILLION)

TABLE 38 REST OF THE WORLD FLIP CHIP TECHNOLOGIES MARKET SIZE AND

FORECAST, BY PACKAGING TYPE, 2015 – 2024 (\$ BILLION)

TABLE 39 REST OF THE WORLD FLIP CHIP TECHNOLOGIES MARKET SIZE AND FORECAST, BY INDUSTRY VERTICAL, 2015 – 2024 (\$ BILLION)

TABLE 40 SAMSUNG ELECTRONICS CO.: COMPANY SNAPSHOT

TABLE 41 ASE GROUP: COMPANY SNAPSHOT

TABLE 42 POWERTECH TECHNOLOGY INC.: COMPANY SNAPSHOT

TABLE 43 UNITED MICROELECTRONICS CORPORATION: COMPANY SNAPSHOT

TABLE 44 INTEL CORPORATION: COMPANY SNAPSHOT

TABLE 45 AMKOR TECHNOLOGY, INC.: COMPANY SNAPSHOT

TABLE 46 TSMC: COMPANY SNAPSHOT

TABLE 47 JIANGSU CHANGJIANG ELECTRONICS TECHNOLOGY CO., LTD.: COMPANY SNAPSHOT

TABLE 48 TEXAS INSTRUMENTS, INC.: COMPANY SNAPSHOT

TABLE 49 SILICONWARE PRECISION INDUSTRIES CO., LTD.: COMPANY SNAPSHOT

I would like to order

Product name: Flip Chip Technologies Market (By Bumping Technology: Copper Pillar, Solder Bumping, Gold Bumping; By Packaging Technology: 3D IC, 2.5D IC and 2D IC; By Packaging Type: Flip Chip SiP Package, Flip Chip PGA Package, Flip Chip BGA Package, Flip Chip LGA Package, and Wafer Level Packaging–CSPnl; By industry: Electronics, Industrial, Automotive & Transport, Healthcare, IT & Telecommunication, Aerospace and Defense; By Geography: North America, Europe, Asia-Pacific and RoW) Global Scenario, Market Size, Outlook, Trend and Forecast, 2015 – 2024

Product link: <https://marketpublishers.com/r/F0A3AC55C12EN.html>

Price: US\$ 3,195.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/F0A3AC55C12EN.html>

To pay by Wire Transfer, please, fill in your contact details in the form below:

First name:
Last name:
Email:
Company:
Address:
City:
Zip code:
Country:
Tel:
Fax:
Your message:

****All fields are required**

Customer signature _____

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms & Conditions at <https://marketpublishers.com/docs/terms.html>

To place an order via fax simply print this form, fill in the information below and fax the completed form to +44 20 7900 3970